

**Product / Package Information**

Package	LFCSP - Punched
Body Size (mm)	10 X 10 X 0.85 (8.2 EP)
Lead Count	72
Terminal Finish	100 Sn

**Environmental Information**

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

**Materials Declaration**

**Molding Compound**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	1.43E-01	86.9	869100	47.14	471420
Thermosets	Epoxy & Phenol Resin	Proprietary	2.10E-02	12.8	127800	6.93	69322
Other inorganic materials	Carbon black	1333-86-4	5.09E-04	0.3	3100	0.17	1682
Subtotal			1.64 E-01	100.00	1000000	54.24	542423

**Leadframe**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	9.75 E-02	97.5	975000	32.21	322097
Copper & its alloys	Iron	7439-89-6	2.35 E-03	2.35	23500	0.78	7763
Copper & its alloys	Zinc	7440-66-6	1.20 E-04	0.12	1200	0.04	396
Copper & its alloys	Phosphorus	7723-14-0	3.00 E-05	0.03	300	0.01	99
Subtotal			1.00 E-01	100.00	1000000	33.04	330356

**Internal Leadframe Plating**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	9.79 E-04	100.0	1000000	0.32	3236

**External Leadframe Plating**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	5.84 E-03	100.0	1000000	1.93	19291

**Bond Wires**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	2.09 E-03	100.0	1000000	0.69	6908

**Chip**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	2.55 E-02	100.0	1000000	8.43	84259

**Die Attach**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	3.18 E-03	77.71	777100	1.05	10511
Thermoset	Epichlorohydrin-formaldehyde-phenol copolymer	9003-36-5	1.27 E-04	3.11	31100	0.04	421
Other organic materials	Epoxy resin, epichlorohydrin-dimer fatty acid	68475-94-5	1.27 E-04	3.11	31100	0.04	421
Other organic materials	Butyrolactone, gamma-	96-48-0	1.27 E-04	3.11	31100	0.04	421
Other organic materials	Poly(oxypropylene)diamine	9046-10-0	1.27 E-04	3.11	31100	0.04	421
Other organic materials	2,6-Diglycidyl phenyl allyl ether oligomer	Unassigned	1.27 E-04	3.11	31100	0.04	421
Other organic materials	Organosilane	TS ref# 10001	1.27 E-04	3.11	31100	0.04	421
Other inorganic materials	Copper(II) oxide	1317-38-0	1.27 E-04	3.11	31100	0.04	421
Other organic materials	Epoxy resin modifier	TS ref# 10038	2.13 E-05	0.52	5200	0.01	70
Subtotal			4.09 E-03	100.0	1000000	1.35	13526

<b>Package Totals</b>			<b>Weight (g)</b>			<b>Percentage (%)</b>	<b>PPM</b>
			3.03 E-01			100	1000000

Note: The information provided in this declaration are true to the best of ADI's knowledge. ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.



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